Recent Progress

- **TWEPP Proceedings:**
  Minor comments received, to be implemented next week

- **Mosaix Probe Card**
  To do next week: Flex only Proposal draft design for MPI

- **Probe Card FPCs - PCBs**
  Breakout board to route HS-data to a scope designed by ITS3: feedback and simulations provided to designers in production – part of the feedbacks might require a second version (not implemented in the current version)

- **Initial preparation of the testing setup in DSF, to be continued**
  Pad Wafer loaded – WP SW guarantees machine operation remotely, has to be polished (ongoing)
  ITS3 Cantilever Probe Card is mounted:
  - Projects for contacting pad wafers ready (MOSAIX / babyMOSAIX) – to be polished tomorrow
  - Pad Wafers contacted succesfully
  - Studies on contacting reliably pad wafers manually ongoing –> aim is to implement SW routines